ABSTRACT OF THE DISCLOSURE

To provide a semiconductor chip mounting method by a flip-chip connection method in which a semiconductor chip can be mounted on a circuit board promptly, electrically and mechanically surely and further at a low cost, a process for pushing a melted thermoplastic resin coat aside by pressing a bump of the bare semiconductor chip on the melted thermoplastic resin coat applying an ultrasonic wave in a state in which the thermoplastic resin coat covering an electrode area on a wiring pattern is heated and melted and touching the bump and the electrode area, a process for bonding the bump and the electrode area by continuously applying an ultrasonic wave in a state in which the bump and the electrode area are touched and a process for cooling and solidifying the melted thermoplastic resin coat and bonding the body of the bare semiconductor chip on the circuit board are provided.

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